



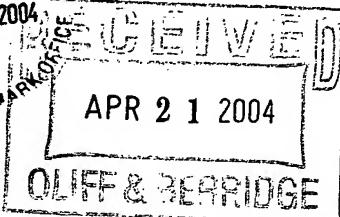
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## FILING RECEIPT



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## Assignment For Published Patent Application

SEIKO EPSON CORPORATION, Tokyo, JAPAN;

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## Foreign Applications

UNITED KINGDOM 0217425.8 07/26/2002

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Early Publication Request: No

Title

Patterning Method  
 Circuit fabrication method